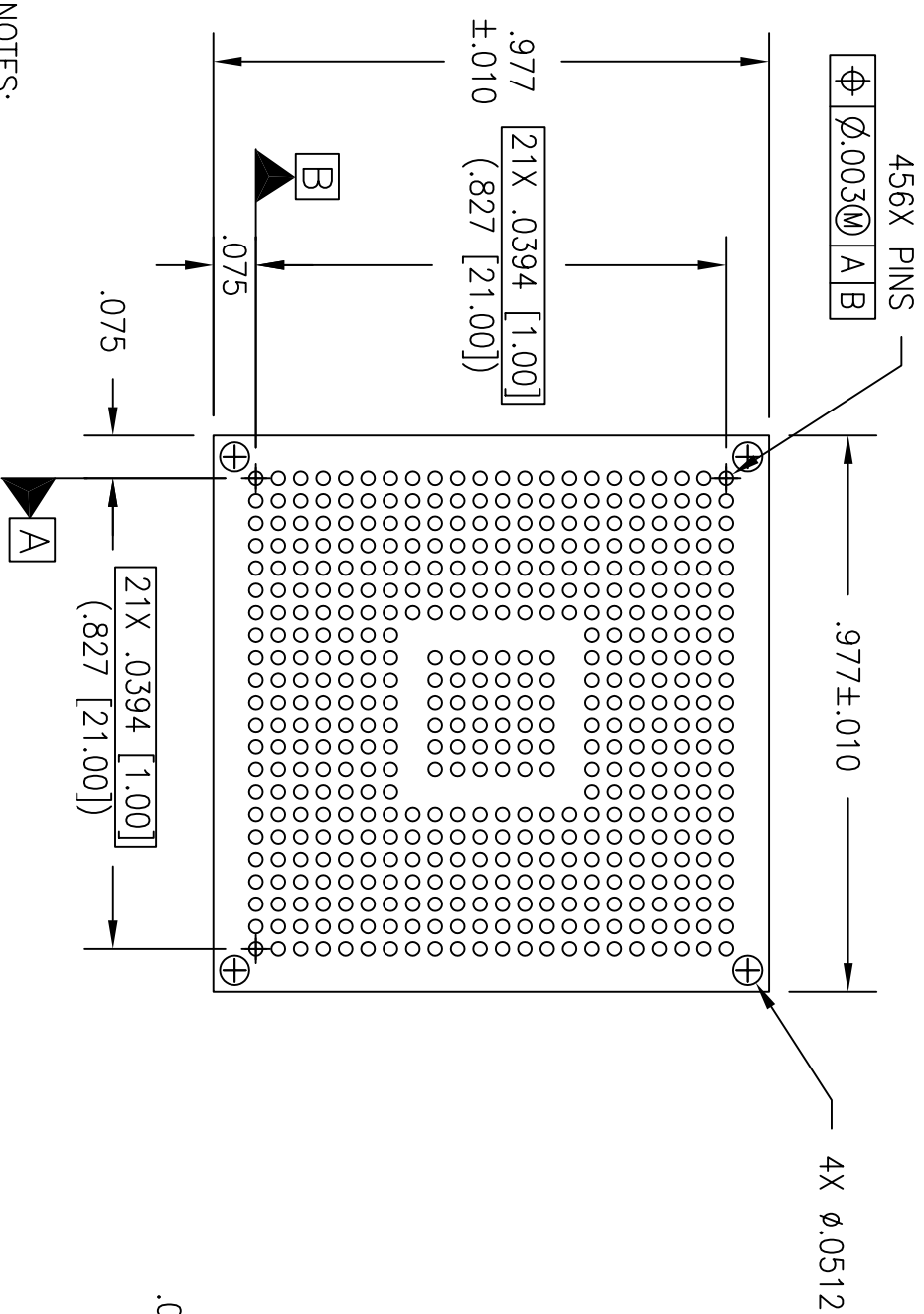
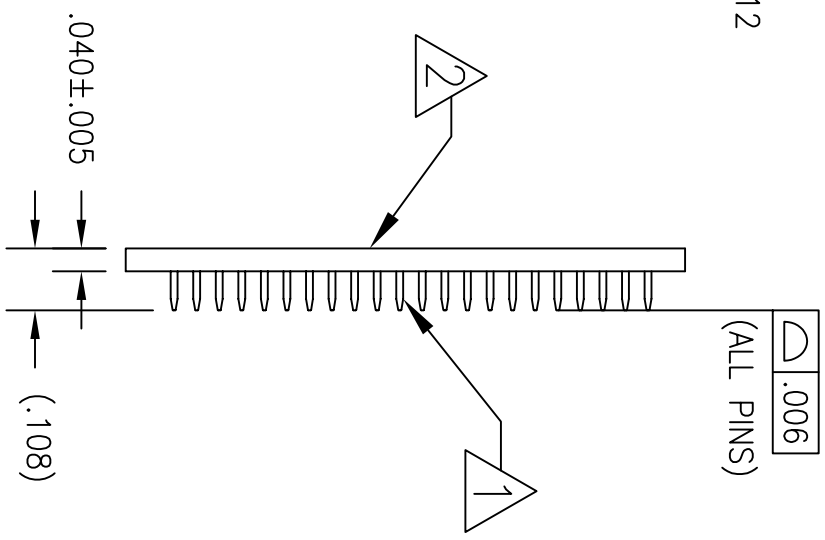


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TOP VIEW



RS VIEW



NOTES:

1. PINS Ø.0117
MATERIAL: PHOSPHOR BRONZE.
PLATING: HARD GOLD OVER NICKEL.
2. INSULATOR MATERIAL: FR4.

REV	DESCRIPTION	ECN	DATE	APPROVAL
1	SALES RELEASE			

CONTRACT NO.		TITLE	
DRAWN BY	DATE	HIL0-BGA PIN BASE	
DESIGNED BY	DATE	22 X 22, 456 PINS	
CHECKER	DATE	1mm PITCH	
UNLESS OTHERWISE SPECIFIED: DIMENSIONS ARE IN INCHES TOLERANCES: ANGLES: FRACTIONS: ± 1/64 DECIMALS: ±.010 .XXX ±.005 .XXXX ±.0005	DATE	SCALE	DRAWING NO.
PROCESS ENG.	DATE	N/A	HLP-220456-B-10
SAWD AS: HLP-220456-B-10.DWG		FINISHED ASST: HLP-220456-B-10	SHEET 1 OF 1

INTERCONNECT SYSTEMS INC.
708 VIA ALONDRA, CAMARILLO, CA 93012

ASIZE

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